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Patent Number

Issue Date

Application Number

10/085,164

Filing Date

February 28, 2002

First Named Inventor

Stephen G. Kelly, et al.

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Michael A. Sileo, Jr.

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Microsemi Corporation

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8131 LBJ Freeway, Suite 800

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75251-1833

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United States of America

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☐

Patentee.

☒

Assignee of record of the entire interest.

Certificate under 37 CFR 3.73(b) is enclosed.

☐

Attorney or agent of record.

Typed or
Printed
Name

Michael A. Sileo, Jr.

Signature

Date

NOTE: Signatures of all the inventors or assignees of record of the entire interest or their representative(s) are required. Submit multiple forms if more than one signature is required, see below.

☒ Total of 2 forms are submitted.

Burden Hour Statement: This form is estimated to take 0.2 hours to complete. Time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Assistant Commissioner for Patents, Washington, DC 20231.



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STATEMENT UNDER 37 CFR 3.73(b)

Applicant/Patent Owner: Microsemi Corporation

Application No./Patent No.: 10/085,164

Filed/Issue Date: February 26, 2002

Entitled: Encapsulated Die Package with Improved Parasitic and Thermal Performance

Microsemi Corporation

a Corporation

(Name of Assignee)

(Type of Assignee, e.g., corporation, partnership, university, government agency, etc.)

states that it is:

1. ☒ the assignee of the entire right, title, and interest; or
2. ☐ an assignee of an undivided part interest

In the patent application/patent identified above by virtue of either:

- A. ☒ An assignment from the inventor(s) of the patent application/patent identified above. The assignment was recorded in the Patent and Trademark Office at Reel _____, Frame _____, or for which a copy thereof is attached.

OR

- B. ☐ A chain of title from the inventor(s), of the patent application/patent identified above, to the current assignee as shown below:

1. From: _____ To: _____
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☐ Additional documents in the chain of title are listed on a supplemental sheet.

- ☐ Copies of assignments or other documents in the chain of title are attached.

(NOTE: A separate copy (i.e., the original assignment document or a true copy of the original document) must be submitted to Assignment Division in accordance with 37 CFR Part 3, if the assignment is to be recorded in the records of the USPTO. See MPEP 302.8)

The undersigned (whose title is supplied below) is empowered to sign this statement on behalf of the assignee.

6/17/02
Date

[Signature]
Signature

Michael A. Stree, Jr.

Typed or printed name

Corporate Counsel

Title

Burden Hour Statement: This form is estimated to take 0.2 hours to complete. Time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Assistant Commissioner for Patents, Washington, DC 20231.

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FORM PTO-1595		RECORDATION FORM COVER SHEET	U.S. Department of Commerce Patent and Trademark Office
Docket Number: A539WTN		Patents Only	
To the Ass't Commissioner for Patents. Please record the attached original documents or copy thereof.			
1. Name of conveying party(ies): Stephen G. Kelly Kenneth R. Philpot Henricus Bernadus Antonius Giesen William E. Doherty, Jr.		2. Name and Address of receiving party(ies): Name: Microsemi Corporation Address: 2381 Morse Avenue City: Irvine, CA 92614 Country: USA Additional name(s) & address(es) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No	
3. Nature of Conveyance: <input checked="" type="checkbox"/> Assignment <input type="checkbox"/> Merger <input type="checkbox"/> Security Agreement <input type="checkbox"/> Change of Name <input type="checkbox"/> Other _____ Execution Date: March 28, 2002, April 2, 2002, April 8, 2002, and April 9, 2002			
4. Application number(s) or patent number(s). <input type="checkbox"/> This document is being filed together with a new application. Execution date of the application: February 26, 2002 Title: ENCAPSULATED DIE PACKAGE WITH IMPROVED PARASITIC AND THERMAL PERFORMANCE A. Patent Application No.(s) S.N 10/085,164 Filed: February 26, 2002 Additional number attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No B. Patent No.(s) Additional numbers attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No			
5. Name and address of party to whom correspondence concerning document should be mailed: Michael A. Sileo, Jr. Microsemi Corporation 8131 LBJ Freeway, Suite 800 Dallas, TX 75251-1333		6. Number of applications and patents involved: <u>(1)</u> 7. Amount of fee enclosed: \$40. 8. Deposit Account No: 50-1752	
DO NOT USE THIS SPACE			
9. Statement and signature. <i>To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.</i> 4-18-02 Date Michael G. Cameron, Reg. No. 50,298			
Total Number of Pages Including Cover Sheet, Attachments and Document: <u>2</u>			

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ATTORNEY'S DOCKET NO.
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ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been accepted on the date set forth below; and

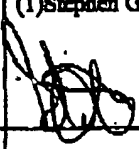
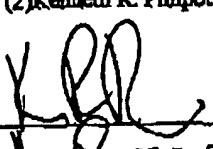
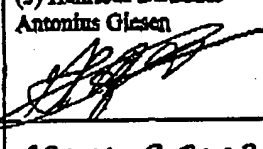
WHEREAS, MICROSEMI CORPORATION, a corporation organized and existing under the laws of the State of California, with its principal office at 2381 Morse Avenue, Irvine, California 92614 may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said MICROSEMI CORPORATION, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefore, and all divisions, reissues, substitutions, continuations, and continuations thereof; and I hereby authorize and request the Commissioner of Patents and Trademarks to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said MICROSEMI CORPORATION, as assignee of my entire right, title and interest.

I also hereby sell and assign to MICROSEMI CORPORATION, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said MICROSEMI CORPORATION, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitution applications, make all lawful oaths, and generally do everything possible to aid said MICROSEMI CORPORATION, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set hand and seal this day and year:

TITLE OF INVENTION	ENCAPSULATED DIE PACKAGE WITH IMPROVED PARASITIC AND THERMAL PERFORMANCE		
SIGNATURE OF INVENTOR AND NAME	(1) Stephen G. Kelly 	(2) Kenneth R. Philpot 	(3) Henricus Bernardus Antonius Giesen 
DATE	APRIL 4 2002	28 MAR 02	APRIL 9, 2002
RESIDENCE (City, County, State)	Melrose, Middlesex, Massachusetts	Nashua, Hillsborough, New Hampshire	Didam, The Netherlands

After recording return Assignment to:

Michael A. Sileo, Jr.
Microsemi Corporation
8131 LBJ Freeway, Suite 800
Dallas, TX 75251-1333

ATTORNEY'S DOCKET NO.
A539WTN

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and

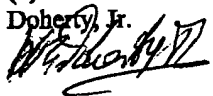
WHEREAS, MICROSEMI CORPORATION, a corporation organized and existing under the laws of the State of California, with its principal office at 2381 Morse Avenue, Irvine, California 92614 may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said MICROSEMI CORPORATION, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefore, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner of Patents and Trademarks to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said MICROSEMI CORPORATION, as assignee of my entire right, title and interest.

I also hereby sell and assign to MICROSEMI CORPORATION, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said MICROSEMI CORPORATION, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said MICROSEMI CORPORATION, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set hand and seal this day and year,

TITLE OF INVENTION	ENCAPSULATED DIE PACKAGE WITH IMPROVED PARASITIC AND THERMAL PERFORMANCE		
SIGNATURE OF INVENTOR AND NAME	(4) William E. Doherty, Jr. 	(5)	(6)
DATE	2 April '02		
RESIDENCE (City, County, State)	Bedford, Middlesex, Massachusetts		

After recording return Assignment to:

Michael A. Sileo, Jr.
Microsemi Corporation
8131 LBJ Freeway, Suite 800
Dallas, TX 75251-1333